

Solution Service for Electronic Devices

- Thermal management, High frequency technology, Lifetime prediction -

TORAY

Toray Research Center, Inc.

Advanced analysis technology

Partnership



FUJITSU

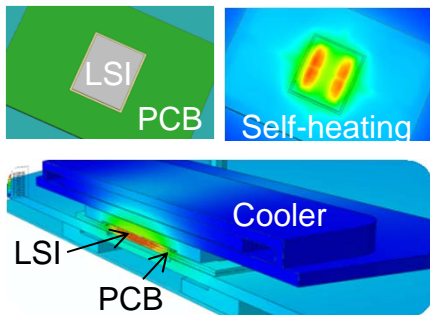
FUJITSU ADVANCED TECHNOLOGIES LIMITED

Electronics packaging, assembly
Simulation technology

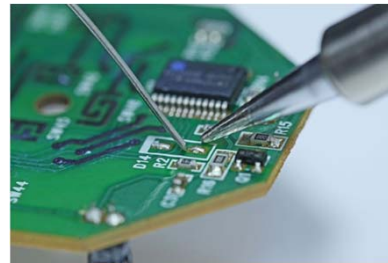
Our service: **Total solution for electronics packaging**

Thermal management

Thermal fluid analysis, Thermal design (optimization)



Estimation of temperature distribution



- Model construction and properties measurement for accurate simulation.
- Design improvement proposal based on simulation result.

High frequency technology

5G communication, Radar for vehicle



ADAS

Sensing



Dielectric properties evaluation for electronic materials

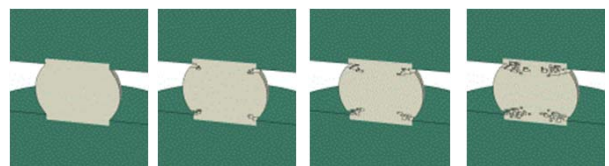
e.g. Dielectric constant and loss

Frequency : 10~95GHz

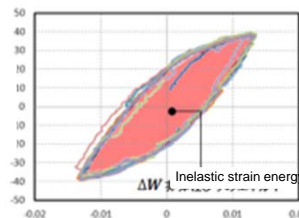
Temp. range : -55°C~160°C

Lifetime prediction

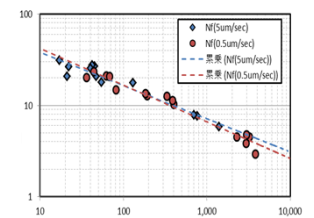
Durability test, Acceleration test



Prediction of crack extension at solder junction



Stress-strain curve



Lifetime curve

Durability evaluation

Degradation of polymer material

Solder junction, Wire bonding, etc.